

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

[IEEE HOME](#) | [SEARCH IEEE](#) | [SHOP](#) | [WEB ACCOUNT](#) | [CONTACT IEEE](#)[Membership](#) | [Publications/Services](#) | [Standards](#) | [Conferences](#) | [Careers/Jobs](#)[Help](#) | [FAQ](#) | [Terms](#) | [IEEE Peer Review](#)[Quick Links](#)[» Advanced Search](#)**Welcome to IEEE Xplore®**

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

- 1) Enter a single keyword, phrase, or Boolean expression.
Example: acoustic imaging (means the phrase acoustic imaging plus any stem variations)
- 2) Limit your search by using search operators and field codes, if desired.
Example: optical <and> (fiber <or> fibre) <in> ti
- 3) Limit the results by selecting Search Options.
- 4) Click Search. See [Search Examples](#)

electronic* and assembly and
(simulat* or model*) and
(performance or metric)

Note: This function returns plural and suffixed forms of the keyword(s).

Search operators: <and> <or> <not> <in> [More](#)

Field codes: au (author), ti (title), ab (abstract), jn (publication name), de (index term) [More](#)

Search Options:**Select publication types:**

- ☒ IEEE Journals
- ☒ IEE Journals
- ☒ IEEE Conference proceedings
- ☒ IEE Conference proceedings
- ☒ IEEE Standards

Select years to search:

From year: All to

2004

Organize search results by:

Sort by: Year

In: Ascending order

List 50 Results per page

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership Publications/Services Standards Conferences Careers/Jobs

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)[Quick Links](#)[» Search Results](#)**Welcome to IEEE Xplore®**

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Your search matched **170** of **991547** documents.A maximum of **170** results are displayed, **50** to a page, sorted by **publication year** in **ascending** order.

You may refine your search by editing the current search expression or entering a new one the text box.

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Then click **Search Again**.**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****Search**

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

[Print Format](#)**1 The Effect of Tandem Band and Amplitude Limiting on the Eb/No Performance of Minimum (Frequency) Shift Keying (MSK)***Mathwich, H.; Balcewicz, J.; Hecht, M.;*

Communications, IEEE Transactions on [legacy, pre - 1988] , Volume: 22 Issue: 10 , Oct 1974

Page(s): 1525 -1540

[\[Abstract\]](#) [\[PDF Full-Text \(1448 KB\)\]](#) **IEEE JNL****2 Analytical models for exterior-type permanent magnet synchronous motors***Rahman, M.;*

Magnetics, IEEE Transactions on , Volume: 23 Issue: 5 , Sep 1987

Page(s): 3625 -3627

[\[Abstract\]](#) [\[PDF Full-Text \(264 KB\)\]](#) **IEEE JNL****3 Human factors analysis of extravehicular servicing of payloads within the space station servicing facility***Reaux, R.A.; Shannon, R.L.; Sheppard, S.B.;*

Aerospace and Electronics Conference, 1988. NAECON 1988., Proceedings of the IEEE 1988 National , 23-27 May 1988

Page(s): 784 -788 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(420 KB\)\]](#) **IEEE CNF****4 Optimal gain tuning using microcomputer simulator***Al-Assadi, S.A.K.;*

Aerospace and Electronics Conference, 1988. NAECON 1988., Proceedings of the IEEE 1988 National , 23-27 May 1988

Page(s): 582 -586 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(296 KB\)\]](#) **IEEE CNF**

5 Speckle effects on intersatellite laser communication

Bremer, W.L.;

Military Communications Conference, 1988. MILCOM 88, Conference record.
'21st Century Military Communications - What's Possible?'. 1988 IEEE , 23-26
Oct. 1988

Page(s): 559 -563 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(320 KB\)\]](#) **IEEE CNF**

6 Internal thermal resistance of a multi-chip packaging design for VLSI-based systems

Lee, Y.C.; Ghaffari, H.T.; Segelken, J.M.;

Electronics Components Conference, 1988., Proceedings of the 38th , 9-11 May
1988

Page(s): 293 -301

[\[Abstract\]](#) [\[PDF Full-Text \(528 KB\)\]](#) **IEEE CNF**

7 Optimization of silicon 8 cm×8 cm wrapthrough space station cells for 'on orbit' operation

Lillington, D.R.; Kukulka, J.R.; Mason, A.V.; Sater, B.L.; Sanchez, J.;

Photovoltaic Specialists Conference, 1988., Conference Record of the Twentieth
IEEE , 26-30 Sept. 1988

Page(s): 934 -939 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(408 KB\)\]](#) **IEEE CNF**

8 A price-performance model and parameter sensitivity analysis for semiconductor assembly equipment

Raghavan, A.S.; Crosby, L.J.;

Semiconductor Manufacturing Science Symposium, 1989. ISMSS 1989.,
IEEE/SEMI International , 22-24 May 1989

Page(s): 95 -98

[\[Abstract\]](#) [\[PDF Full-Text \(196 KB\)\]](#) **IEEE CNF**

9 Fine pitch package mounting with TAB tape

Dehaine, G.; Joly, J.;

Electronic Manufacturing Technology Symposium, 1989, Proceedings. Japan
IEMT Symposium, Sixth IEEE/CHMT International , 26-28 April 1989

Page(s): 73 -78

[\[Abstract\]](#) [\[PDF Full-Text \(508 KB\)\]](#) **IEEE CNF**

10 Accurate ILS and MLS performance evaluation in presence of site errors

Mahapatra, P.R.; Poullose, M.M.;

Aerospace and Electronics Conference, 1989. NAECON 1989., Proceedings of the IEEE 1989 National , 22-26 May 1989

Page(s): 167 -174 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(432 KB\)\]](#) **IEEE CNF**

11 An empirically based analytical approach to process technology and international location choice for electronics assembly

Tatikonda, M.V.; Suri, R.; Sanders, J.L.; Mody, A.;

Engineering Management Conference, 1990. 'Management Through the Year 2000 - Gaining the Competitive Advantage', 1990 IEEE International , 21-24 Oct. 1990

Page(s): 359 -364

[\[Abstract\]](#) [\[PDF Full-Text \(332 KB\)\]](#) **IEEE CNF**

12 Modeling and analysis of a new product development in electronic sub-assembly manufacturing

Joseph, L.A.; Watt, J.T.; Wigglesworth, N.;

Simulation Conference, 1990. Proceedings., Winter , 9-12 Dec. 1990

Page(s): 899 -903

[\[Abstract\]](#) [\[PDF Full-Text \(392 KB\)\]](#) **IEEE CNF**

13 A flexible simulation framework for evaluating multi-level, heuristic-based production control strategies

Taylor, G.D., Jr.;

Simulation Conference, 1990. Proceedings., Winter , 9-12 Dec. 1990

Page(s): 567 -569

[\[Abstract\]](#) [\[PDF Full-Text \(324 KB\)\]](#) **IEEE CNF**

14 Estimating front end throughput: where has all the data gone [PCB manufacture]

Babin, T.S.; Lofgren, C.B.;

Electronic Manufacturing Technology Symposium, 1990 Proceedings, 'Competitive Manufacturing for the Next Decade'. IEMT Symposium, Ninth IEEE/CHMT International , 1-3 Oct. 1990

Page(s): 98 -102

[\[Abstract\]](#) [\[PDF Full-Text \(396 KB\)\]](#) **IEEE CNF**

15 Modeling of performance-related design trade-offs in multi-chip assemblies

Palusinski, O.A.; Hohl, J.H.;

Electronics Manufacturing Technology Symposium, 1991., Eleventh IEEE/CHMT International , 16-18 Sept. 1991

Page(s): 333 -336

[\[Abstract\]](#) [\[PDF Full-Text \(348 KB\)\]](#) **IEEE CNF**

16 Mechanical integrity of the IC device package-a key factor in achieving failure free product performance

Witzman, S.; Giroux, Y.;

Electronic Components and Technology Conference, 1991. Proceedings., 41st , 11-16 May 1991

Page(s): 450 -456

[\[Abstract\]](#) [\[PDF Full-Text \(568 KB\)\]](#) **IEEE CNF**

17 An isolated laser module based on a modularity concept

Chaoui, G.M.; Holbrook, W.R.; Barks, G.S., Jr.; Gaebe, C.E.; Jameson, R.S.; Miller, T.J.; Schwenk, C.M.; Smeltz, P.D.; Wiand, G.T.; Yeh, X.-L.; Young, C.E.;

Electronic Components and Technology Conference, 1991. Proceedings., 41st , 11-16 May 1991

Page(s): 172 -175

[\[Abstract\]](#) [\[PDF Full-Text \(316 KB\)\]](#) **IEEE CNF**

18 Optimization of Futurebus+backplane structures

Florescu, V.; Lupien, R.C.;

Electronic Components and Technology Conference, 1992. Proceedings., 42nd , 18-20 May 1992

Page(s): 287 -292

[\[Abstract\]](#) [\[PDF Full-Text \(304 KB\)\]](#) **IEEE CNF**

19 Thin QFP design and development

Woosley, A.; Djennas, F.; McShane, M.; Primeaux, F.; Kraft, D.; Reinhardt, R.; Bigler, J.; Casto, J.;

Electronic Components and Technology Conference, 1992. Proceedings., 42nd , 18-20 May 1992

Page(s): 429 -437

[\[Abstract\]](#) [\[PDF Full-Text \(416 KB\)\]](#) **IEEE CNF**

20 Cost saving opportunities with multichip modules*Mavroides, J.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 15 Issue: 3, June 1992

Page(s): 295 -298

[\[Abstract\]](#) [\[PDF Full-Text \(312 KB\)\]](#) **IEEE JNL**

21 Integrated range image segmentation using connectionist paradigm*Ghosal, S.; Mehrotra, R.;*

Industrial Electronics, Control, and Instrumentation, 1993. Proceedings of the IECON '93., International Conference on, 15-19 Nov. 1993

Page(s): 1690 -1695 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(456 KB\)\]](#) **IEEE CNF**

22 Fuzzy logic based on-line MRAC tuning of slip gain for an indirect vector-controlled induction motor drive*Sousa, G.C.D.; Bose, B.K.; Kim, K.S.;*

Industrial Electronics, Control, and Instrumentation, 1993. Proceedings of the IECON '93., International Conference on, 15-19 Nov. 1993

Page(s): 1003 -1008 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(420 KB\)\]](#) **IEEE CNF**

23 A disturbance observer for robotic assembly of odd form electronic components*Chan, S.P.; Lee, C.Y.; Mital, D.P.;*

Industrial Electronics, Control, and Instrumentation, 1993. Proceedings of the IECON '93., International Conference on, 15-19 Nov. 1993

Page(s): 1395 -1400 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(420 KB\)\]](#) **IEEE CNF**

24 Study of soldering for VLSI/FLC spatial light modulators*Wei Lin; Lee, Y.C.; Johnson, K.M.;*

Electronic Components and Technology Conference, 1993. Proceedings., 43rd, 1-4 June 1993

Page(s): 491 -497

[\[Abstract\]](#) [\[PDF Full-Text \(492 KB\)\]](#) **IEEE CNF**

25 Proceedings of IEEE 43rd Electronic Components and Technology Conference (ECTC '93)

Electronic Components and Technology Conference, 1993. Proceedings., 43rd, 1-4 June 1993

[\[Abstract\]](#) [\[PDF Full-Text \(268 KB\)\]](#) **IEEE CNF**

26 Design factors and their effect on PCB assembly yield - Statistical and neural network predictive models

Li, Y.; Mahajan, R.L.; Tong, J.;

Electronic Manufacturing Technology Symposium, 1993, Fifteenth IEEE/CHMT International, 4-6 Oct. 1993

Page(s): 353 -361

[\[Abstract\]](#) [\[PDF Full-Text \(624 KB\)\]](#) **IEEE CNF**

27 Manufacturing systems simulated

Jayaraman, R.; Toole, P., Jr.;

Spectrum, IEEE, Volume: 30 Issue: 9, Sept. 1993

Page(s): 60 -62

[\[Abstract\]](#) [\[PDF Full-Text \(404 KB\)\]](#) **IEEE JNL**

28 Packaging techniques for microengineering devices

Stockham, N.R.;

Moving and Flexing Microstructures - their Design, Modelling and Production, IEE Colloquium on, 15 Mar 1994

Page(s): 5/1

[\[Abstract\]](#) [\[PDF Full-Text \(60 KB\)\]](#) **IEE CNF**

29 A compact LTCC multilayer multiport stripline coupler network for wideband low loss power combining/splitting

Gipprich, J.W.; Dickens, L.E.; Hayes, R.E.; Restivo, M.A.;

Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on, 2-4 Nov. 1994

Page(s): 167 -169

[\[Abstract\]](#) [\[PDF Full-Text \(284 KB\)\]](#) **IEEE CNF**

30 Analysis of heretofor unsolved electromagnetic simulation problems in high performance multichip modules and printed circuit boards: simulation and measurement of power plane noise and internal inductance

Techentin, R.W.; Lei, G.T.; Staniszewski, A.J.; Pan, G.W.; Schwab, D.J.; Gilbert, B.K.;

Precision Electromagnetic Measurements, 1994. Digest., 1994 Conference on, 27 June-1 July 1994

Page(s): 142

[\[Abstract\]](#) [\[PDF Full-Text \(84 KB\)\]](#) **IEEE CNF**

31 Ultra-reliable digital avionics (URDA) processor architecture*Branstetter, R.; Harper, A.; Denton, L.;*

Aerospace and Electronics Conference, 1994. NAECON 1994., Proceedings of the IEEE 1994 National , 23-27 May 1994

Page(s): 274 -280 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(552 KB\)\]](#) **IEEE CNF****32 A hybrid analytical/intelligent approach to the modeling and control of DEDS***Kamen, E.W.; Vachtsevanos, G.; Doustmohammadi, A.; Mahmood, W.;*

Computer-Aided Control System Design, 1994. Proceedings., IEEE/IFAC Joint Symposium on , 7-9 March 1994

Page(s): 47 -53

[\[Abstract\]](#) [\[PDF Full-Text \(456 KB\)\]](#) **IEEE CNF****33 Predicting thermal contact resistance in circuit card assemblies***Kunkel, S.H.; Peck, W.M.;*

Thermal Phenomena in Electronic Systems, 1994. I-THERM IV. 'Concurrent Engineering and Thermal Phenomena', InterSociety Conference on , 4-7 May 1994

Page(s): 91 -100

[\[Abstract\]](#) [\[PDF Full-Text \(500 KB\)\]](#) **IEEE CNF****34 Surface mount assembly failure statistics and failure free time***Clech, J.-P.M.; Noctor, D.M.; Manock, J.C.; Lynott, G.W.; Baders, F.E.;*

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1-4 May 1994

Page(s): 487 -497

[\[Abstract\]](#) [\[PDF Full-Text \(1024 KB\)\]](#) **IEEE CNF****35 Low cost molded packaging for optical data links***Robinson, S.D.; Acarlar, M.S.; Chen, Y.C.; Manzione, L.T.; Shevchuk, G.J.;**Stefanik, D.;*

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1-4 May 1994

Page(s): 312 -316

[\[Abstract\]](#) [\[PDF Full-Text \(464 KB\)\]](#) **IEEE CNF****36 Impact of moisture/reflow induced delaminations on integrated circuit thermal performance***Conrad, T.R.; Shook, R.L.;*

Electronic Components and Technology Conference, 1994. Proceedings., 44th ,

1-4 May 1994
Page(s): 527 -531

[\[Abstract\]](#) [\[PDF Full-Text \(516 KB\)\]](#) **IEEE CNF**

37 Panoramic imaging perimeter sensor design and modeling

Pritchard, D.A.;

Security Technology, 1994. Proceedings. Institute of Electrical and Electronics Engineers 28th Annual 1994 International Carnahan Conference on , 12-14 Oct. 1994

Page(s): 20 -25

[\[Abstract\]](#) [\[PDF Full-Text \(440 KB\)\]](#) **IEEE CNF**

38 Petri nets and industrial applications: A tutorial

Zurawski, R.; MengChu Zhou;

Industrial Electronics, IEEE Transactions on , Volume: 41 Issue: 6 , Dec. 1994

Page(s): 567 -583

[\[Abstract\]](#) [\[PDF Full-Text \(1548 KB\)\]](#) **IEEE JNL**

39 Pointing grade fiber optic gyroscope

Killian, K.M.;

Aerospace and Electronic Systems Magazine, IEEE , Volume: 9 Issue: 7 , July 1994

Page(s): 6 -10

[\[Abstract\]](#) [\[PDF Full-Text \(392 KB\)\]](#) **IEEE JNL**

40 Optimization and simulation of the printed circuit assembly

Feldmann, K.; Franke, J.; Rothhaupt, A.;

Components, Packaging, and Manufacturing Technology, Part A, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 17 Issue: 2 , June 1994

Page(s): 277 -281

[\[Abstract\]](#) [\[PDF Full-Text \(444 KB\)\]](#) **IEEE JNL**

41 Modelling of the initial stages of the anisotropic adhesive joint assembly process

Mannan, S.H.; Whalley, D.C.; Ogunjimi, Y.O.; Williams, D.J.;

Electronic Manufacturing Technology Symposium, 1995, Proceedings of 1995 Japan International, 18th IEEE/CPMT International , 4-6 Dec. 1995

Page(s): 142 -145

[\[Abstract\]](#) [\[PDF Full-Text \(372 KB\)\]](#) **IEEE CNF**

42 Design of a compact, high speed optical transceiver using two step overmolding

Anigbo, F.C.J.; Robinson, S.D.; Broutin, S.L.; Shevchuk, G.J.; Stefanik, D.;
Electronic Components and Technology Conference, 1995. Proceedings., 45th ,
21-24 May 1995
Page(s): 1104 -1109

[\[Abstract\]](#) [\[PDF Full-Text \(576 KB\)\]](#) **IEEE CNF**

43 Influence of computer chassis design on metal fabrication waste streams

Sheng, P.; Willis, B., III; Shiovitz, A.;
Electronics and the Environment, 1995. ISEE., Proceedings of the 1995 IEEE
International Symposium on , 1-3 May 1995
Page(s): 209 -215

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) **IEEE CNF**

44 18 fiber cylindrical cable connector (FLASH contract)

Roe, C.A.;
Electronic Components and Technology Conference, 1995. Proceedings., 45th ,
21-24 May 1995
Page(s): 161 -169

[\[Abstract\]](#) [\[PDF Full-Text \(840 KB\)\]](#) **IEEE CNF**

45 Electronic box-level reliability assessment using computer modeling and simulation

Chiang, A.C.; Barker, D.B.; Krolewski, J.G.; Cushing, M.J.;
Reliability and Maintainability Symposium, 1995. Proceedings., Annual , 16-19
Jan. 1995
Page(s): 49 -53

[\[Abstract\]](#) [\[PDF Full-Text \(1080 KB\)\]](#) **IEEE CNF**

46 Design and characterization of three-dimensional aluminum nitride multichip modules

Palmquist, S.L.; Jensen, R.J.; Jacobsen, W.F.; Spielberger, R.K.;
Multi-Chip Module Conference, 1995. MCMC-95, Proceedings., 1995 IEEE , 31
Jan.-2 Feb. 1995
Page(s): 177 -182

[\[Abstract\]](#) [\[PDF Full-Text \(744 KB\)\]](#) **IEEE CNF**

47 **An ultra-miniature rubidium frequency standard with two-cell scheme**
Koyama, Y.; Matsuura, H.; Atsumi, K.; Nakajima, Y.; Chiba, K.;
Frequency Control Symposium, 1995. 49th., Proceedings of the 1995 IEEE
International , 31 May-2 June 1995
Page(s): 33 -38

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) **IEEE CNF**

48 **Modeling nonlinear features of V tail aircraft using MNN**
Deergha Rao, K.;
Aerospace and Electronic Systems, IEEE Transactions on , Volume: 31 Issue: 2 ,
April 1995
Page(s): 841 -845

[\[Abstract\]](#) [\[PDF Full-Text \(324 KB\)\]](#) **IEEE JNL**

49 **Study of 18-cm long single-sided AC-coupled silicon microstrip detectors**
Kollipara, R.T.; Arodzero, A.; Bashindzhagyan, G.; Brau, J.E.; Frey, R.; Gao, D.;
Mason, D.; Sinev, N.; Strom, D.; Yang, X.;
Nuclear Science, IEEE Transactions on , Volume: 42 Issue: 2 , April 1995
Page(s): 92 -101

[\[Abstract\]](#) [\[PDF Full-Text \(820 KB\)\]](#) **IEEE JNL**

50 **A disturbance observer for robot manipulators with application to electronic components assembly**
Chan, S.P.;
Industrial Electronics, IEEE Transactions on , Volume: 42 Issue: 5 , Oct. 1995
Page(s): 487 -493

[\[Abstract\]](#) [\[PDF Full-Text \(644 KB\)\]](#) **IEEE JNL**

1 2 3 4 [\[Next\]](#)

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#)
[Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#)
[No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2003 IEEE — All rights reserved

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership Publications/Services Standards Conferences Careers/Jobs

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)[Quick Links](#)[» Search Results](#)**Welcome to IEEE Xplore®**

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
 - ☐ Establish IEEE Web Account
 - ☐ Access the IEEE Member Digital Library
- [Print Format](#)

Your search matched **170** of **991547** documents.A maximum of **170** results are displayed, **50** to a page, sorted by **publication year** in **ascending** order.

You may refine your search by editing the current search expression or entering a new one the text box.

Then click **Search Again**.[Search Again](#)**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****51 Thermal behavior simulation of quartz resonators in an oven environment***Galliou, S.;*Ultrasonics, Ferroelectrics and Frequency Control, IEEE Transactions on ,
Volume: 42 Issue: 5 , Sept. 1995

Page(s): 832 -839

[\[Abstract\]](#) [\[PDF Full-Text \(592 KB\)\]](#) **IEEE JNL****52 CAD models of a QFP-24 pin package for radiofrequency applications***Ndagijimana, F.; Chilo, J.;*Electrical Performance of Electronic Packaging, 1996., IEEE 5th Topical Meeting ,
28-30 Oct. 1996

Page(s): 103 -105

[\[Abstract\]](#) [\[PDF Full-Text \(196 KB\)\]](#) **IEEE CNF****53 Conductive polymer bump interconnects***Jong-Kai Lin; Drye, J.; Lytle, W.; Scharr, T.; Subrahmanyam, R.; Sharma, R.;*Electronic Components and Technology Conference, 1996. Proceedings., 46th ,
28-31 May 1996

Page(s): 1059 -1068

[\[Abstract\]](#) [\[PDF Full-Text \(1452 KB\)\]](#) **IEEE CNF****54 Multifiber connector end face attributes for optimal connector performance***Kevern, J.; Harper, D.; Knasel, D.; Knight, K.; Satake, T.;*Electronic Components and Technology Conference, 1996. Proceedings., 46th ,
28-31 May 1996

Page(s): 936 -941

[\[Abstract\]](#) [\[PDF Full-Text \(556 KB\)\]](#) **IEEE CNF**

55 Area array packaging technologies for high-performance computer workstations and multiprocessors

Chung, T.C.; Ghahghahi, F.; Oberlin, B.; Carey, D.; Nelson, D.;

Electronic Components and Technology Conference, 1996. Proceedings., 46th , 28-31 May 1996

Page(s): 902 -910

[\[Abstract\]](#) [\[PDF Full-Text \(1048 KB\)\]](#) **IEEE CNF**

56 Thermal characterization of a 3-dimensional memory module

Tae-Hyun Kim; JoongHyun Baek; Seol, S.H.; Kim, J.J.; Kim, Y.S.; Sun, Y.B.; Oh, S.Y.;

Semiconductor Thermal Measurement and Management Symposium, 1996.

SEMI-THERM XII. Proceedings., Twelfth Annual IEEE , 5-7 March 1996

Page(s): 14 -18

[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **IEEE CNF**

57 A virtual prototyping environment for multi-scale, multi-disciplinary simulation of electronics packaging of MCMs

Przekwas, A.J.; Jiang, Y.; Athavale, M.M.; Wang, Z.J.; van der Zijp, J.;

Thermal Phenomena in Electronic Systems, 1996. I-THERM V., Inter-Society Conference on , 29 May-1 June 1996

Page(s): 352 -358

[\[Abstract\]](#) [\[PDF Full-Text \(820 KB\)\]](#) **IEEE CNF**

58 Bottom leaded plastic (BLP) package: a new design with enhanced solder joint reliability

Young-Gon Kim; Bongtae Han; Shin Choi; Myung-Ki Kim;

Electronic Components and Technology Conference, 1996. Proceedings., 46th , 28-31 May 1996

Page(s): 448 -452

[\[Abstract\]](#) [\[PDF Full-Text \(528 KB\)\]](#) **IEEE CNF**

59 Modeling the cost of ownership of assembly and inspection

Dance, D.L.; DiFloria, T.; Jimenez, D.W.;

Components, Packaging, and Manufacturing Technology, Part C, IEEE

Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 19 Issue: 1 , Jan. 1996

Page(s): 57 -60

[\[Abstract\]](#) [\[PDF Full-Text \(428 KB\)\]](#) **IEEE JNL**

60 Design standards for effective MCM design

Ladd, S.K.;

Multichip Modules, 1997., 6th International Conference on , 2-4 April 1997

Page(s): 193 -195

[\[Abstract\]](#) [\[PDF Full-Text \(212 KB\)\]](#) **IEEE CNF**

61 Thermal modeling of grease-type interface material in PPGA application

Chia-Pin Chiu; Solbrekken, G.L.; Chung, Y.D.;

Semiconductor Thermal Measurement and Management Symposium, 1997.

SEMI-THERM XIII., Thirteenth Annual IEEE , 28-30 Jan. 1997

Page(s): 57 -63

[\[Abstract\]](#) [\[PDF Full-Text \(520 KB\)\]](#) **IEEE CNF**

62 Board on chip-ball grid array (BOC-BGA™) package. A new design for high frequency application (package design and reliability)

Chee-Kiang Yew; Pang-Hup Ong; Yong-Khim Swee; Min-Yu Chan; Siu-Waf Low; Toh, J.; Chan, J.; Chew-Weng Leong;

Electronic Components and Technology Conference, 1997. Proceedings., 47th , 18-21 May 1997

Page(s): 353 -357

[\[Abstract\]](#) [\[PDF Full-Text \(556 KB\)\]](#) **IEEE CNF**

63 Integration of environmental factors in process modeling for printed circuit board manufacturing. I. Assembly

Worhach, P.; Sheng, P.;

Electronics and the Environment, 1997. ISEE-1997., Proceedings of the 1997

IEEE International Symposium on , 5-7 May 1997

Page(s): 218 -225

[\[Abstract\]](#) [\[PDF Full-Text \(884 KB\)\]](#) **IEEE CNF**

64 Deep space one basebody control: validating the data path from computer to thruster

Pingree, P.J.; Leang, C.F.; Basilio, R.R.;

Digital Avionics Systems Conference, 1997. 16th DASC., AIAA/IEEE , Volume: 1 , 26-30 Oct. 1997

Page(s): 4.5 -6-13 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(628 KB\)\]](#) **IEEE CNF**

65 **Self-tuning control of brushless servo drive for a high performance tracking manipulator**

Cheung, J.W.F.; Chung, A.W.K.; Cheung, N.C.;

Power Electronics and Drive Systems, 1997. Proceedings., 1997 International Conference on , Volume: 1 , 26-29 May 1997

Page(s): 297 -301 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(384 KB\)\]](#) **IEEE CNF**

66 **Test chip development to support standardization efforts**

Bright, B.;

Electronics Manufacturing Technology Symposium, 1997., Twenty-First IEEE/CPMT International , 13-15 Oct. 1997

Page(s): 184 -191

[\[Abstract\]](#) [\[PDF Full-Text \(1000 KB\)\]](#) **IEEE CNF**

67 **Cost considerations for integrating flip chip and chip on board technologies into high volume manufacturing areas**

Roney, R.;

Electronics Manufacturing Technology Symposium, 1997., Twenty-First IEEE/CPMT International , 13-15 Oct. 1997

Page(s): 269 -273

[\[Abstract\]](#) [\[PDF Full-Text \(360 KB\)\]](#) **IEEE CNF**

68 **Cybertronics: interactive simulation game for design and manufacturing education**

Sanderson, A.; Millard, D.; Jennings, W.; Krawczyk, T.; Slattery, D.; Sanderson, S.W.;

Frontiers in Education Conference, 1997. 27th Annual Conference. 'Teaching and Learning in an Era of Change'. Proceedings. , Volume: 3 , 5-8 Nov. 1997

Page(s): 1595 -1606 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(1652 KB\)\]](#) **IEEE CNF**

69 **Using integral coil to drive a two-axis gyroscope**

Wei Shen Wu;

Aerospace and Electronic Systems, IEEE Transactions on , Volume: 33 Issue: 1 , Jan. 1997

Page(s): 322 -328

[\[Abstract\]](#) [\[PDF Full-Text \(380 KB\)\]](#) **IEEE JNL**

70 Improvement of the absorbing clamp coupling and screening attenuation measurements and standards for symmetric and coaxial cables and connecting hardware (connectors and cable assemblies)

Bech, E.;

SCreening Effectiveness Measurements (Ref. No. 1998/452), IEE Colloquium on ,
6 May 1998

Page(s): 5/1 -5/9

[\[Abstract\]](#) [\[PDF Full-Text \(428 KB\)\]](#) **IEEE CNF**

71 Mixed hardware/software applications on dynamically reconfigurable hardware

Canas Ferreira, J.; Silva Matos, J.;

Electronics, Circuits and Systems, 1998 IEEE International Conference on ,
Volume: 1 , 7-10 Sept. 1998

Page(s): 97 -100 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(344 KB\)\]](#) **IEEE CNF**

72 Position and energy resolution of a new gamma-ray detector based on a single CsI(Tl) scintillator coupled to a silicon drift chamber array

Fiorini, C.; Longoni, A.; Boschini, L.; Perotti, F.; Labanti, C.; Rossi, E.; Lechner, P.; Struder, L.;

Nuclear Science Symposium, 1998. Conference Record. 1998 IEEE , Volume: 2 ,
8-14 Nov. 1998

Page(s): 796 -802 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(524 KB\)\]](#) **IEEE CNF**

73 Thermal fatigue life prediction for solder joints with the consideration of damage evolution

Zhang, X.; Lee, S.-W.R.;

Electronics Packaging Technology Conference, 1998. Proceedings of 2nd , 8-10
Dec. 1998

Page(s): 279 -285

[\[Abstract\]](#) [\[PDF Full-Text \(364 KB\)\]](#) **IEEE CNF**

74 Test head scheduling in a semiconductor test facility

Bahadur, S.; Mohanraj, S.; Tirupati, D.;

Electronics Manufacturing Technology Symposium, 1998. Twenty-Third
IEEE/CPMT , 19-21 Oct. 1998

Page(s): 131 -135

[\[Abstract\]](#) [\[PDF Full-Text \(505 KB\)\]](#) **IEEE CNF**

75 Methodology for predicting pin-fin fan-sink performance*Wirtz, R.A.; Zheng, N.;*

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998.

ITHERM '98. The Sixth Intersociety Conference on , 27-30 May 1998

Page(s): 303 -309

[\[Abstract\]](#) [\[PDF Full-Text \(516 KB\)\]](#) **IEEE CNF****76 Surface mount conductive adhesives with superior impact resistance***Vons, S.A., Jr.; Tong, Q.K.; Kuder, R.; Shenfield, D.;*

Advanced Packaging Materials, 1998. Proceedings. 1998 4th International

Symposium on , 15-18 March 1998

Page(s): 261 -267

[\[Abstract\]](#) [\[PDF Full-Text \(508 KB\)\]](#) **IEEE CNF****77 Thermal management issues and evaluation of a novel, flexible substrate, 3-dimensional (3-D) packaging concept***Brown, W.D.; Malshe, A.P.; Railkar, T.A.; Lenihan, T.G.; Stone, J.W.; Sommers, W.T.; Schaper, L.W.;*

Multichip Modules and High Density Packaging, 1998. Proceedings. 1998 7th International Conference on , 15-17 April 1998

Page(s): 135 -140

[\[Abstract\]](#) [\[PDF Full-Text \(584 KB\)\]](#) **IEEE CNF****78 Enhancement of underfill performance for flip-chip applications by use of silane additives***Vincent, M.B.; Meyers, L.; Wong, C.P.;*

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28 May 1998

Page(s): 125 -131

[\[Abstract\]](#) [\[PDF Full-Text \(780 KB\)\]](#) **IEEE CNF****79 Three dimensional die surface stress measurements in delaminated and non-delaminated plastic packages***Zou, Y.; Suhling, J.C.; Jaeger, R.C.; Ali, H.;*

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28 May 1998

Page(s): 1223 -1234

[\[Abstract\]](#) [\[PDF Full-Text \(2712 KB\)\]](#) **IEEE CNF****80 RF flip-module BGA package***Low, Y.L.; Degani, Y.; Guinn, K.V.; Dudderrar, T.D.; Gregus, J.; Frye, R.C.;*

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28

May 1998
Page(s): 1115 -1119

[\[Abstract\]](#) [\[PDF Full-Text \(460 KB\)\]](#) **IEEE CNF**

81 **GHz flip chip-an overview**

Boustedt, K.;

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28

May 1998

Page(s): 297 -302

[\[Abstract\]](#) [\[PDF Full-Text \(556 KB\)\]](#) **IEEE CNF**

82 **Thermal simulation and validation of the fast static RAM 164-lead FC-PBGA package with investigations of package thermal performance in a generic CPU module**

Eyman, M.; Johnson, Z.; Joiner, B.;

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28

May 1998

Page(s): 62 -69

[\[Abstract\]](#) [\[PDF Full-Text \(708 KB\)\]](#) **IEEE CNF**

83 **System-level design models and implementation techniques**

Lavagno, L.; Sangiovanni-Vincentelli, A.;

Application of Concurrency to System Design, 1998. Proceedings., 1998

International Conference on , 23-26 March 1998

Page(s): 24 -32

[\[Abstract\]](#) [\[PDF Full-Text \(188 KB\)\]](#) **IEEE CNF**

84 **Concurrent thermal design for high-power electronics**

Lall, B.S.;

Semiconductor Thermal Measurement and Management Symposium, 1998.

SEMI-THERM Proceedings 1998., Fourteenth Annual IEEE , 10-12 March 1998

Page(s): 95 -103

[\[Abstract\]](#) [\[PDF Full-Text \(596 KB\)\]](#) **IEEE CNF**

85 **Fabrication process of copper lead frame chip scale package (LF-CSP)**

Jong Tae Moon; Sung Hak Hong; Seung Wook Yoon; Chang Jun Park; Yoon Hwa Choi; Jae Myun Kim; Jong Hyun Lee; Ja Ryoung Kim; Yo Hwan Koh;

Electronic Components and Technology Conference, 1999. 1999 Proceedings.

49th , 1-4 June 1999

Page(s): 1235 -1240

[\[Abstract\]](#) [\[PDF Full-Text \(504 KB\)\]](#) **IEEE CNF**

86 Gain and G/T of reconfigurable active receive antennas-a parametric approach

Kraft, U.R.;

Antennas and Propagation Society, 1999. IEEE International Symposium 1999 , Volume: 4 , 11-16 July 1999

Page(s): 2250 -2253 vol.4

[\[Abstract\]](#) [\[PDF Full-Text \(168 KB\)\]](#) **IEEE CNF**

87 Modern military avionics power supplies a DFM challenge

Walker, W.D.;

Aerospace Conference, 1999. Proceedings. 1999 IEEE , Volume: 2 , 6-13 March 1999

Page(s): 193 -198 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(1096 KB\)\]](#) **IEEE CNF**

88 Implementation of generalized impedance control for robot manipulators

Chan, S.P.;

Industrial Electronics Society, 1999. IECON '99 Proceedings. The 25th Annual Conference of the IEEE , Volume: 1 , 29 Nov.-3 Dec. 1999

Page(s): 418 -423 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(412 KB\)\]](#) **IEEE CNF**

89 The test requirements model (TeRM) communicating test information throughout the product life cycle

Shombert, L.A.; Davis, D.C.; Bukata, E.M.;

Test Conference, 1999. Proceedings. International , 28-30 Sept. 1999

Page(s): 868 -876

[\[Abstract\]](#) [\[PDF Full-Text \(720 KB\)\]](#) **IEEE CNF**

90 High thermal performance silicon heat spreaders with microwhisker structure

Hammel, E.; Nagl, C.; Nicolics, J.; Hanreich, G.;

Electronics Manufacturing Technology Symposium, 1999. Twenty-Fourth IEEE/CPMT , 18-19 Oct. 1999

Page(s): 426 -432

[\[Abstract\]](#) [\[PDF Full-Text \(832 KB\)\]](#) **IEEE CNF**

91 Flip chip contacts for high current conducting assemblies*Jung, E.; Kemp, A.; Isa, R.; Kloeser, J.; Aschenbrenner, R.; Reichl, H.;*

Electronics Manufacturing Technology Symposium, 1999. Twenty-Fourth IEEE/CPMT , 18-19 Oct. 1999

Page(s): 120 -126

[\[Abstract\]](#) [\[PDF Full-Text \(532 KB\)\]](#) **IEEE CNF****92 Force disturbance compensation for an AC brushless linear motor***Bassi, E.; Benzi, F.; Moro, F.; Buja, G.;*

Industrial Electronics, 1999. ISIE '99. Proceedings of the IEEE International Symposium on , Volume: 3 , 12-16 July 1999

Page(s): 1350 -1354 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(224 KB\)\]](#) **IEEE CNF****93 Electrical and mechanical modeling of embedded capacitors***Yang Rao; Jianmin Qu; Wong, C.P.;*

Electronic Components and Technology Conference, 1999. 1999 Proceedings. 49th , 1-4 June 1999

Page(s): 506 -509

[\[Abstract\]](#) [\[PDF Full-Text \(424 KB\)\]](#) **IEEE CNF****94 Thermal and electrical performance and reliability results for cavity-up enhanced BGAs***Hayden, T.F.; Harvey, P.M.; Schueller, R.D.; Clatanoff, W.J.;*

Electronic Components and Technology Conference, 1999. 1999 Proceedings. 49th , 1-4 June 1999

Page(s): 638 -644

[\[Abstract\]](#) [\[PDF Full-Text \(692 KB\)\]](#) **IEEE CNF****95 Design characterization of microwave antenna BGA interconnect structure using test-validated physics-of-failure methods***Pietila, D.A.; Rassaian, M.; Brice-Heames, K.;*

Reliability Physics Symposium Proceedings, 1999. 37th Annual. 1999 IEEE International , 23-25 March 1999

Page(s): 347 -355

[\[Abstract\]](#) [\[PDF Full-Text \(932 KB\)\]](#) **IEEE CNF****96 Performance and behavioral modeling of avionics subsystems***Hanna, W.A.; Macke, M.W.; Traversy, R.M.; Martinez, M.J.;*

Digital Avionics Systems Conference, 1999. Proceedings. 18th , Volume: 1/17 pp. vol.1 , 24-29 Oct. 1999

Page(s): 1.B.5-1 -1.B.5-9 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(732 KB\)\]](#) **IEEE CNF**

97 Preventing conductive white residue formation by modifying the manufacturing process

Palmer, M.A.; Metz, J.D.; Sinni, A.M.; Soon, J.; Maguire, J.F.;

Electronics Packaging Manufacturing, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on], Volume: 22 Issue: 2, April 1999

Page(s): 156 -165

[\[Abstract\]](#) [\[PDF Full-Text \(280 KB\)\]](#) **IEEE JNL**

98 A model for optimizing the assembly and disassembly of electronic systems

Sandborn, P.A.; Murphy, C.F.;

Electronics Packaging Manufacturing, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on], Volume: 22 Issue: 2, April 1999

Page(s): 105 -117

[\[Abstract\]](#) [\[PDF Full-Text \(856 KB\)\]](#) **IEEE JNL**

99 Strategies to improve electrode positioning and safety in cochlear implants

Rebscher, S.J.; Heilmann, M.; Bruszewski, W.; Talbot, N.H.; Snyder, R.L.;

Merzenich, M.M.;

Biomedical Engineering, IEEE Transactions on, Volume: 46 Issue: 3, March 1999

Page(s): 340 -352

[\[Abstract\]](#) [\[PDF Full-Text \(772 KB\)\]](#) **IEEE JNL**

100 Use of fault tree analysis for evaluation of system-reliability improvements in design phase

Krasich, M.;

Reliability and Maintainability Symposium, 2000. Proceedings, Annual, 24-27

Jan. 2000

Page(s): 1 -7

[\[Abstract\]](#) [\[PDF Full-Text \(420 KB\)\]](#) **IEEE CNF**

[\[Prev\]](#) [1](#) [2](#) [3](#) [4](#) [\[Next\]](#)

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#)
[Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#)
[No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2003 IEEE — All rights reserved

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership Publications/Services Standards Conferences Careers/Jobs

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)[Quick Links](#)[» Search Results](#)**Welcome to IEEE Xplore®**

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Your search matched **170** of **991547** documents.A maximum of **170** results are displayed, **50** to a page, sorted by **publication year** in **ascending** order.

You may refine your search by editing the current search expression or entering a new one the text box.

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Then click **Search Again**.electronic* and assembly and (simulat* or model*) al **Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****Search**

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

[Print Format](#)

101 Power flip-chip assembly for space application using HBT in Ku band
Vendier, O.; George, S.; Frayse, J.-P.; Rogeaux, E.; Drevon, C.; Cazaux, J.-L.; Floriot, D.; Caillas-Devignes, N.; Blanck, H.; Doser, W.; Auxemery, P.; de Ceuninck, W.; Petersen, R.; Haese, N.; Rolland, P.-A.;
Gallium Arsenide Integrated Circuit (GaAs IC) Symposium, 2000. 22nd Annual ,
5-8 Nov 2000
Page(s): 157 -159

[\[Abstract\]](#) [\[PDF Full-Text \(348 KB\)\]](#) **IEEE CNF**

102 Application of SU-8 in flip chip bump micromachining for millimeter wave applications
Wong, A.; Linton, D.;
Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd , 5-7 Dec 2000
Page(s): 204 -209

[\[Abstract\]](#) [\[PDF Full-Text \(660 KB\)\]](#) **IEEE CNF**

103 Analysis of ACA/ACF package using equivalent spring method
Chiang, K.N.; Chang, C.W.; Lin, J.D.;
Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd , 5-7 Dec 2000
Page(s): 110 -116

[\[Abstract\]](#) [\[PDF Full-Text \(592 KB\)\]](#) **IEEE CNF**

104 Study of stepper motor performance in a five-axis robot
Zein El Din, A.; El-Farmawy, M.;
Power Electronics and Motion Control Conference, 2000. Proceedings. PIEMC

2000. The Third International , Volume: 2 , 15-18 Aug. 2000
Page(s): 823 -831 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(452 KB\)\]](#) **IEEE CNF**

105 **Qualification guidelines for automotive packaging devices**

Raghunathan, R.; Sitaraman, S.K.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000.

ITHERM 2000. The Seventh Intersociety Conference on , Volume: 1 , 23-26 May 2000 -392

[\[Abstract\]](#) [\[PDF Full-Text \(640 KB\)\]](#) **IEEE CNF**

106 **Multiphysics modelling for electronics design**

Parry, J.; Bailey, C.; Aldham, C.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000.

ITHERM 2000. The Seventh Intersociety Conference on , Volume: 2 , 23-26 May 2000

Page(s): 86 -93 vol. 2

[\[Abstract\]](#) [\[PDF Full-Text \(608 KB\)\]](#) **IEEE CNF**

107 **Modelling technology to predict flip-chip assembly**

Wheeler, D.; Bailey, C.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000.

ITHERM 2000. The Seventh Intersociety Conference on , Volume: 2 , 23-26 May 2000

Page(s): 79 -85 vol. 2

[\[Abstract\]](#) [\[PDF Full-Text \(308 KB\)\]](#) **IEEE CNF**

108 **Design for manufacturing of RF MCM-L**

Hashemi, H.; Langari, A.; Coccioli, R.; Megahed, M.;

Electrical Performance of Electronic Packaging, 2000, IEEE Conference on. , 23-25 Oct. 2000

Page(s): 283 -287

[\[Abstract\]](#) [\[PDF Full-Text \(284 KB\)\]](#) **IEEE CNF**

109 **The evaluation of anisotropically conductive film for use in portable electronic products**

Curran, K.; Holloway, M.; Lennox, A.;

Adhesive Joining and Coating Technology in Electronics Manufacturing, 2000.

Proceedings. 4th International Conference on , 18-21 June 2000

Page(s): 199

[\[Abstract\]](#) [\[PDF Full-Text \(44 KB\)\]](#) **IEEE CNF**

110 Electromagnetic characterization of IWS wiring integration assemblies

Irby, C.; Grady, T.H.; Scully, R.C.;

Electromagnetic Compatibility, 2000. IEEE International Symposium on , Volume: 1 , 21-25 Aug. 2000

Page(s): 203 -208 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(464 KB\)\]](#) **IEEE CNF**

111 Effects of no-clean flux residue on the performance of flip-chip devices

Todd, M.;

Advanced Packaging Materials: Processes, Properties and Interfaces, 2000. Proceedings. International Symposium on , 6-8 March 2000

Page(s): 180 -182

[\[Abstract\]](#) [\[PDF Full-Text \(156 KB\)\]](#) **IEEE CNF**

112 Methodology for minimizing power with DSP code

Wiratunga, S.; Gebotys, C.;

Electrical and Computer Engineering, 2000 Canadian Conference on , Volume: 1 , 7-10 March 2000

Page(s): 293 -296 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) **IEEE CNF**

113 A VHDL library of IP cores for power drive and motion control applications

Pimentel, J.C.G.; Hoang Le-Huy;

Electrical and Computer Engineering, 2000 Canadian Conference on , Volume: 1 , 7-10 March 2000

Page(s): 184 -188 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(412 KB\)\]](#) **IEEE CNF**

114 Ceramic column grid array technology with coated solder columns

Bor Zen Hong; Ray, S.K.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings. 50th , 21-24 May 2000

Page(s): 1347 -1353

[\[Abstract\]](#) [\[PDF Full-Text \(732 KB\)\]](#) **IEEE CNF**

115 Analytical model to study interfacial delamination propagation in a multi-layered electronic packaging structure under thermal loading

Hu, H.; Xie, W.; Sitaraman, S.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Page(s): 1526 -1534

[\[Abstract\]](#) [\[PDF Full-Text \(728 KB\)\]](#) **IEEE CNF**

116 Warpage studies of HDI test vehicles during various thermal profiling

Petriccione, G.J.; Ume, I.C.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Page(s): 1640 -1646

[\[Abstract\]](#) [\[PDF Full-Text \(672 KB\)\]](#) **IEEE CNF**

117 New course development in electronic products and systems cost analysis

Sandborn, P.; Allen, D.T.; Murphy, C.F.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Page(s): 1021 -1026

[\[Abstract\]](#) [\[PDF Full-Text \(708 KB\)\]](#) **IEEE CNF**

118 New CBGA package with improved 2nd level reliability

Pendse, R.; Afshari, B.; Butel, N.; Leibovitz, J.; Hosoi, Y.; Shimada, M.; Maeda, K.; Maeda, M.; Yonekura, H.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Page(s): 1189 -1197

[\[Abstract\]](#) [\[PDF Full-Text \(896 KB\)\]](#) **IEEE CNF**

119 Predictive reliability modeling for flipchip interconnect bump extrusion

Lucero, A.E.; Dias, R.; Pavey, T.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Page(s): 619 -623

[\[Abstract\]](#) [\[PDF Full-Text \(536 KB\)\]](#) **IEEE CNF**

120 Investigation of the thermal performance of micro-whisker structured silicon heatspreaders for power devices

Nicolics, J.; Hanreich, G.; Stangl, G.;

Microelectronics, 2000. Proceedings. 2000 22nd International Conference on , Volume: 2 , 14-17 May 2000

Page(s): 671 -674 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(260 KB\)\]](#) **IEEE CNF**

121 Design of hybrid controller for assembly task based on evaluation with HMM

Nozaki, T.; Hirana, K.; Itabashi, K.; Suzuki, T.; Okuma, S.; Fujiwara, F.;

Industrial Electronics Society, 2000. IECON 2000. 26th Annual Conference of the IEEE , Volume: 3 , 22-28 Oct. 2000

Page(s): 2082 -2087 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(445 KB\)\]](#) **IEEE CNF**

122 Performance and physics of quantum-dot lasers with self-assembled columnar-shaped and 1.3- μ m emitting InGaAs quantum dots

Sugawara, M.; Mukai, K.; Nakata, Y.; Otsubo, K.; Ishikawa, H.;

Selected Topics in Quantum Electronics, IEEE Journal on , Volume: 6 Issue: 3 , May-June 2000

Page(s): 462 -474

[\[Abstract\]](#) [\[PDF Full-Text \(536 KB\)\]](#) **IEEE JNL**

123 Neural-network-based motor rolling bearing fault diagnosis

Li, B.; Chow, M.-Y.; Tipsuwan, Y.; Hung, J.C.;

Industrial Electronics, IEEE Transactions on , Volume: 47 Issue: 5 , Oct. 2000

Page(s): 1060 -1069

[\[Abstract\]](#) [\[PDF Full-Text \(948 KB\)\]](#) **IEEE JNL**

124 A fuzzy system for automotive fault diagnosis: fast rule generation and self-tuning

Yi Lu; Tie Qi Chen; Hamilton, B.;

Vehicular Technology, IEEE Transactions on , Volume: 49 Issue: 2 , March 2000

Page(s): 651 -660

[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **IEEE JNL**

125 Selection and evaluation of materials for future system-on-package (SOP) substrate

Markondeya Raj, P.; Shinotani, K.; Mancheol Seo; Bhattacharya, S.; Sundaram, V.; Zama, S.; Jicun Lu; Zweben, C.; White, G.E.; Tummala, R.R.;

Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 1193 -1197

[\[Abstract\]](#) [\[PDF Full-Text \(344 KB\)\]](#) **IEEE CNF**

126 High K polymer-ceramic nano-composite development, characterization, and modeling for embedded capacitor RF application
Yang Rao; Jireh Yue; Wong, C.P.;
Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 1408 -1412

[\[Abstract\]](#) [\[PDF Full-Text \(208 KB\)\]](#) **IEEE CNF**

127 Mold delamination and die fracture analysis of mechatronic packages
Mercado, L.L.; Wieser, H.; Hauck, T.;
Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 903 -910

[\[Abstract\]](#) [\[PDF Full-Text \(580 KB\)\]](#) **IEEE CNF**

128 High performance flip chip PBGA development
Stone, B.; Czarnowski, J.M.; Guajardo, J.R.;
Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 997 -1002

[\[Abstract\]](#) [\[PDF Full-Text \(684 KB\)\]](#) **IEEE CNF**

129 Over GHz low-power RF clock distribution for a multiprocessor digital system
Woonghwan Ryu; Albert Lu Chee Wai; Fan Wei; Wai Lai Lai; Joungcho Kim;
Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 133 -140

[\[Abstract\]](#) [\[PDF Full-Text \(412 KB\)\]](#) **IEEE CNF**

130 Stacked thin dice packaging
Pienimaa, S.K.; Valtanen, J.; Heikkila, R.; Ristolainen, E.;
Electronic Components and Technology Conference, 2001. Proceedings., 51st ,
29 May-1 June 2001
Page(s): 361 -366

[\[Abstract\]](#) [\[PDF Full-Text \(820 KB\)\]](#) **IEEE CNF**

131 PID controller using the TMS320C31 DSK with online parameter adjustment for real-time DC motor speed and position control

Jianxin Tang;

Industrial Electronics, 2001. Proceedings. ISIE 2001. IEEE International Symposium on , Volume: 2 , 12-16 June 2001

Page(s): 786 -791 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(320 KB\)\]](#) **IEEE CNF**

132 RF electrical simulation of embedded capacitor

Yang Rao; Jianmin Qu; Wong, C.P.;

Advanced Packaging Materials: Processes, Properties and Interfaces, 2001. Proceedings. International Symposium on , 11-14 March 2001

Page(s): 286 -292

[\[Abstract\]](#) [\[PDF Full-Text \(488 KB\)\]](#) **IEEE CNF**

133 Assessing product design alternatives with respect to environmental performance and sustainability: a case study for circuit pack faceplates

Mosovsky, J.; Dispenza, J.; Dickinson, D.; Morabito, J.; Caudill, R.; Alli, N.;

Electronics and the Environment, 2001. Proceedings of the 2001 IEEE International Symposium on , 7-9 May 2001

Page(s): 252 -257

[\[Abstract\]](#) [\[PDF Full-Text \(452 KB\)\]](#) **IEEE CNF**

134 Substrate designs to improve die crack damage in CSP

Kao, N.; Wang, Y.P.; Chou, S.; Tsai, Y.L.; Her, T.D.;

Electronic Materials and Packaging, 2001. EMAP 2001. Advances in , 19-22 Nov. 2001

Page(s): 444 -449

[\[Abstract\]](#) [\[PDF Full-Text \(507 KB\)\]](#) **IEEE CNF**

135 Gain-scheduled L₂-gain based control of a flexible parameter-varying robot link

Rieber, J.M.; Taylor, D.G.;

Industrial Electronics Society, 2001. IECON '01. The 27th Annual Conference of the IEEE , Volume: 1 , 29 Nov.-2 Dec. 2001

Page(s): 552 -557 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(522 KB\)\]](#) **IEEE CNF**

136 Development of 6-DOF haptic interface for tele-micromanipulation systems

Ando, N.; Morioka, K.; Szemes, P.T.; Hashimoto, H.;

Industrial Electronics Society, 2001. IECON '01. The 27th Annual Conference of the IEEE , Volume: 1 , 29 Nov.-2 Dec. 2001

Page(s): 444 -449 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(611 KB\)\]](#) **IEEE CNF**

137 Controller optimization for minimum position error signals of hard disk drives

Ho Seong Lee;

Industrial Electronics, IEEE Transactions on , Volume: 48 Issue: 5 , Oct. 2001

Page(s): 945 -950

[\[Abstract\]](#) [\[PDF Full-Text \(168 KB\)\]](#) **IEEE JNL**

138 On the use of yielded cost in modeling electronic assembly processes

Becker, D.V.; Sandborn, P.A.;

Electronics Packaging Manufacturing, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on] , Volume: 24 Issue: 3 , July 2001

Page(s): 195 -202

[\[Abstract\]](#) [\[PDF Full-Text \(192 KB\)\]](#) **IEEE JNL**

139 Neural network modeling with confidence bounds: a case study on the solder paste deposition process

Ho, S.L.; Xie, M.; Tang, L.C.; Xu, K.; Goh, T.N.;

Electronics Packaging Manufacturing, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on] , Volume: 24 Issue: 4 , Oct. 2001

Page(s): 323 -332

[\[Abstract\]](#) [\[PDF Full-Text \(232 KB\)\]](#) **IEEE JNL**

140 Intelligent material handling: development and implementation of a matrix-based discrete-event controller

Mireles, J., Jr.; Lewis, F.L.;

Industrial Electronics, IEEE Transactions on , Volume: 48 Issue: 6 , Dec. 2001

Page(s): 1087 -1097

[\[Abstract\]](#) [\[PDF Full-Text \(314 KB\)\]](#) **IEEE JNL**

141 Single level integrated packaging modules for high performance electronic systems

Li-Rong Zheng; Tenhunen, H.;

Advanced Packaging, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on] , Volume: 24 Issue: 4 , Nov. 2001

Page(s): 477 -485

[\[Abstract\]](#) [\[PDF Full-Text \(235 KB\)\]](#) **IEEE JNL**

142 Analytical approach to evaluate shear stress in flip chip interconnection using NCA/ACF

Se Young Yang; Soon-Bok Lee; Woon-Seong Kwon; Kyung-Wook Paik;

Electronic Materials and Packaging, 2002. Proceedings of the 4th International Symposium on , 4-6 Dec. 2002

Page(s): 204 -209

[\[Abstract\]](#) [\[PDF Full-Text \(379 KB\)\]](#) **IEEE CNF**

143 Modeling and sensorless optimal controller design for an electric power assist steering system

Parmar, M.; Hung, J.Y.;

IECON 02 [Industrial Electronics Society, IEEE 2002 28th Annual Conference of the] , Volume: 3 , 5-8 Nov. 2002

Page(s): 1784 -1789 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(444 KB\)\]](#) **IEEE CNF**

144 Design for enhancing reliability of LD chip in a 10Gps optoelectronic package

Ma Yiyi; Sudharsanam, K.; Pamidighantam, R.; Ishimura, E.;

Electronics Packaging Technology Conference, 2002. 4th , 10-12 Dec. 2002

Page(s): 164 -169

[\[Abstract\]](#) [\[PDF Full-Text \(550 KB\)\]](#) **IEEE CNF**

145 40 Gbit/s "fish ladder" signal path and connectorized signal path in ceramic and organic packages for OC768 applications

Pillai, E.R.;

Electrical Performance of Electronic Packaging, 2002 , 21-23 Oct. 2002

Page(s): 239 -242

[\[Abstract\]](#) [\[PDF Full-Text \(406 KB\)\]](#) **IEEE CNF**

146 Evolutionary test program induction for microprocessor design verification

Corno, F.; Cumani, G.; Sonza Reorda, M.; Squillero, G.;

Test Symposium, 2002. (ATS '02). Proceedings of the 11th Asian , 18-20 Nov. 2002
Page(s): 368 -373

[\[Abstract\]](#) [\[PDF Full-Text \(285 KB\)\]](#) **IEEE CNF**

147 Effect of underfill fillet configuration on flip chip package reliability
Nguyen, L.; Nguyen, H.;
Electronics Manufacturing Technology Symposium, 2002. IEMT 2002. 27th Annual IEEE/SEMI International , 17-18 July 2002
Page(s): 291 -303

[\[Abstract\]](#) [\[PDF Full-Text \(972 KB\)\]](#) **IEEE CNF**

148 Possibilities and limitations of no-flow fluxing underfill
Hurley, J.M.; Xiaoyun Ye; Berfield, T.;
Electronics Manufacturing Technology Symposium, 2002. IEMT 2002. 27th Annual IEEE/SEMI International , 17-18 July 2002
Page(s): 88 -93

[\[Abstract\]](#) [\[PDF Full-Text \(466 KB\)\]](#) **IEEE CNF**

149 Thermal performance of IMS/spl trade/ dielectrics: data and prediction
Gundale, B.P.; Misra, S.;
Thermal and Thermomechanical Phenomena in Electronic Systems, 2002. IThERM 2002. The Eighth Intersociety Conference on , 30 May-1 June 2002
Page(s): 1083 -1088

[\[Abstract\]](#) [\[PDF Full-Text \(579 KB\)\]](#) **IEEE CNF**

150 An integrated approach to flow, thermal and mechanical modeling of electronics devices
Parry, J.; Marooney, C.; Warner, M.; Bailey, C.; Pericleous, K.;
Thermal and Thermomechanical Phenomena in Electronic Systems, 2002. IThERM 2002. The Eighth Intersociety Conference on , 30 May-1 June 2002
Page(s): 862 -868

[\[Abstract\]](#) [\[PDF Full-Text \(819 KB\)\]](#) **IEEE CNF**

[\[Prev\]](#) [1](#) [2](#) [3](#) [4](#) [\[Next\]](#)

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#)
[Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#)
[No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2003 IEEE — All rights reserved